



US 20070000612A1

(19) **United States**

(12) **Patent Application Publication**

Nozawa et al.

(10) **Pub. No.: US 2007/0000612 A1**

(43) **Pub. Date:**

Jan. 4, 2007

(54) SUBSTRATE PROCESSING DEVICE

(76) Inventors: **Toshihisa Nozawa**, Hyogo (JP);
Takaaki Matsuoka, Tokyo (JP)

Correspondence Address:
CROWELL & MORING LLP
INTELLECTUAL PROPERTY GROUP
P.O. BOX 14300
WASHINGTON, DC 20044-4300 (US)

(21) Appl. No.: **10/569,378**

(22) PCT Filed: **Aug. 26, 2004**

(86) PCT No.: **PCT/JP04/12276**

§ 371(c)(1),
(2), (4) Date: **Feb. 24, 2006**

(30) Foreign Application Priority Data

Sep. 10, 2003 (JP) 2003-309367

Publication Classification

(51) Int. Cl.

H01L 21/306 (2006.01)

C23C 16/00 (2006.01)

(52) **U.S. Cl. 156/345.32; 414/939; 118/719**

(57) ABSTRACT

A substrate processing apparatus includes a plurality of process chambers (20) for applying a process to substrate accommodated therein and a conveyance case (24) that conveys the accommodated substrates to the process chambers (20) and a transfer mechanism that moves the conveyance case (24) along a moving path. The conveyance case accommodates the substrates in an isolated state from an external atmosphere. The plurality of process chambers (20) are arranged in an aligned state on both sides of a moving path of the conveyance case (24). The conveyance case (24) has two conveyance ports (24a) in response to conveyance ports (20a) of the process chambers (20) arranged in alignment in two rows.

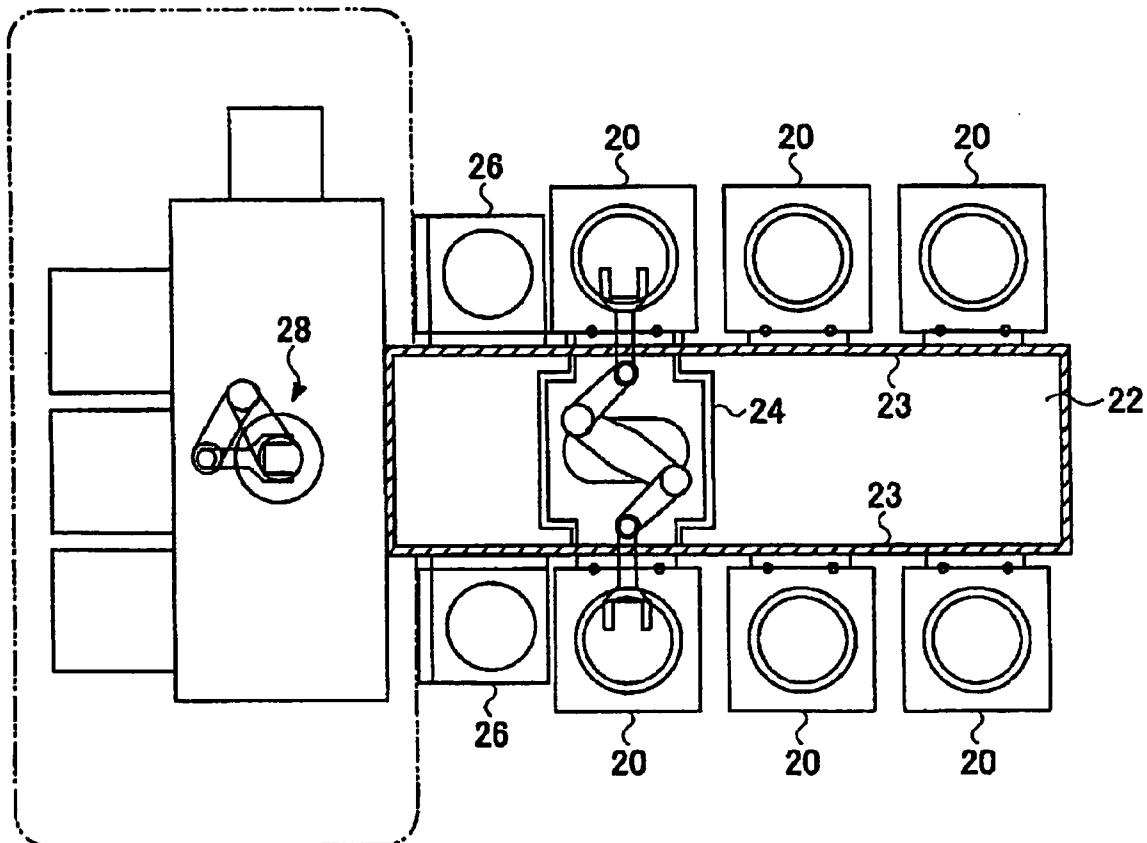


FIG.1

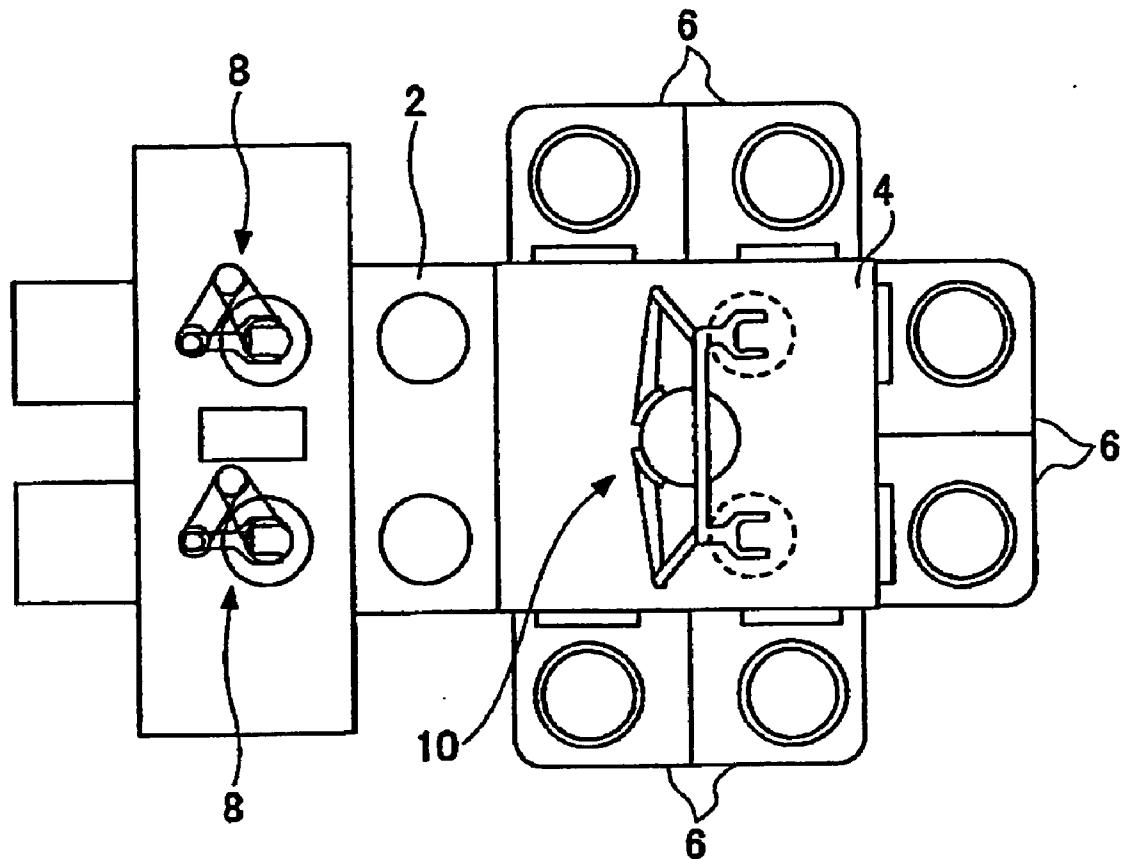


FIG.2

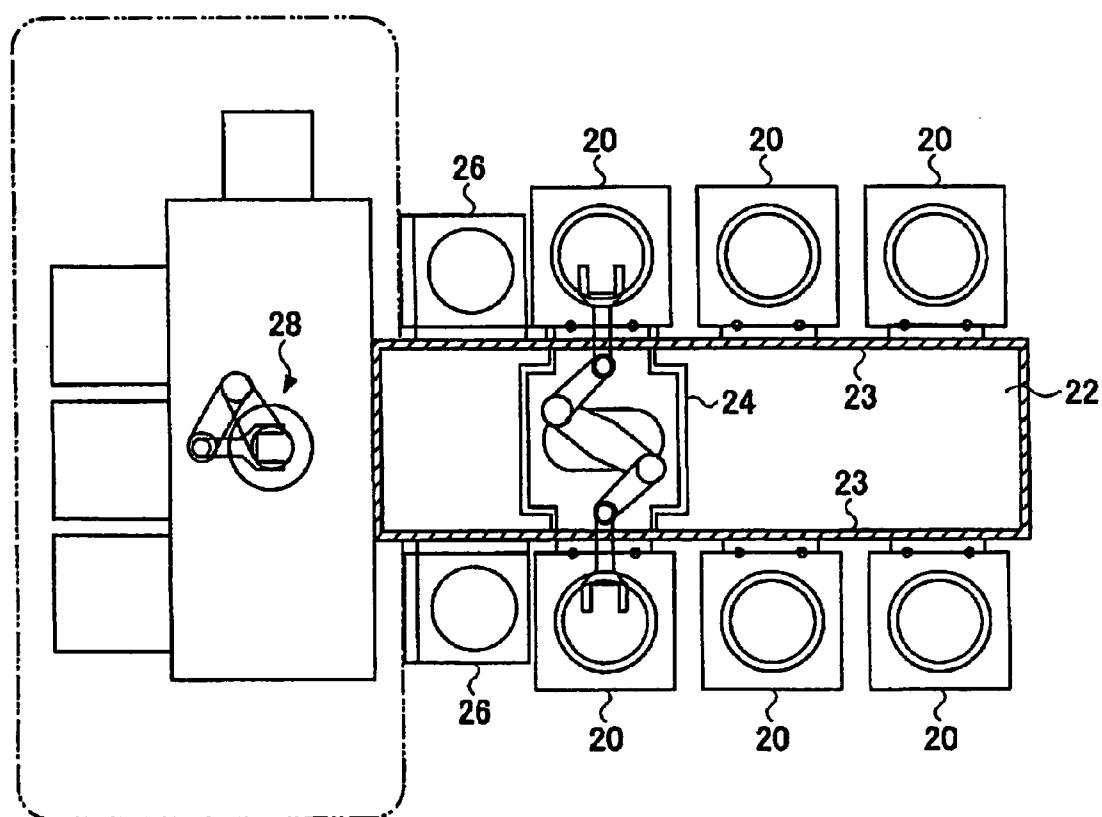


FIG.3

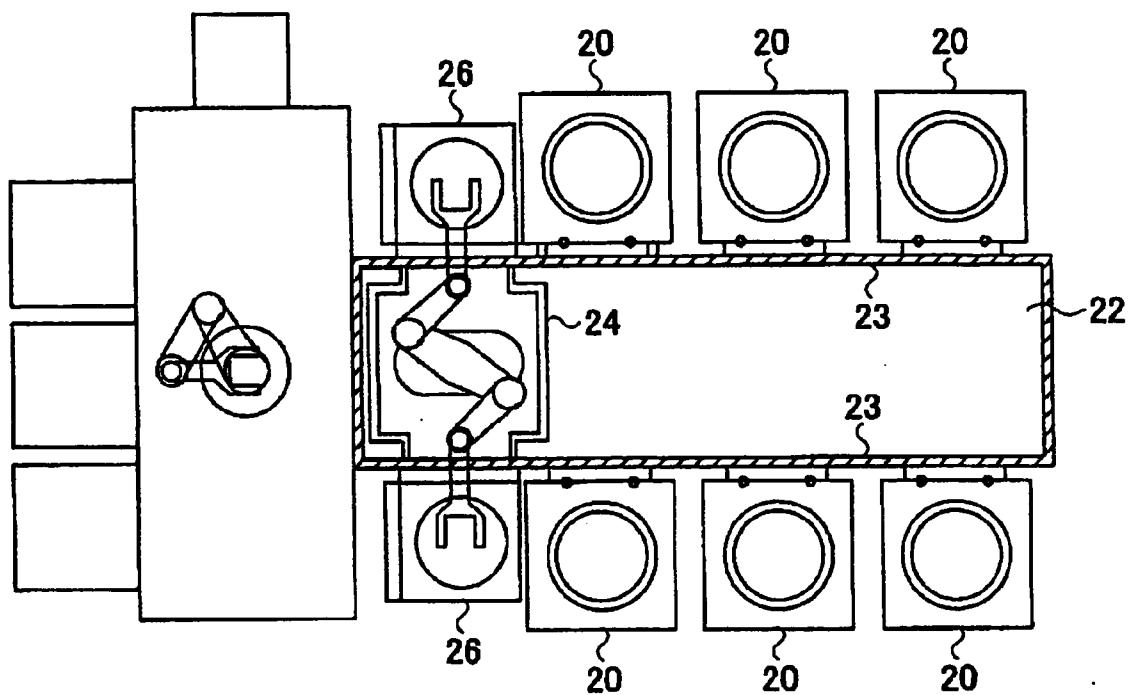


FIG. 4

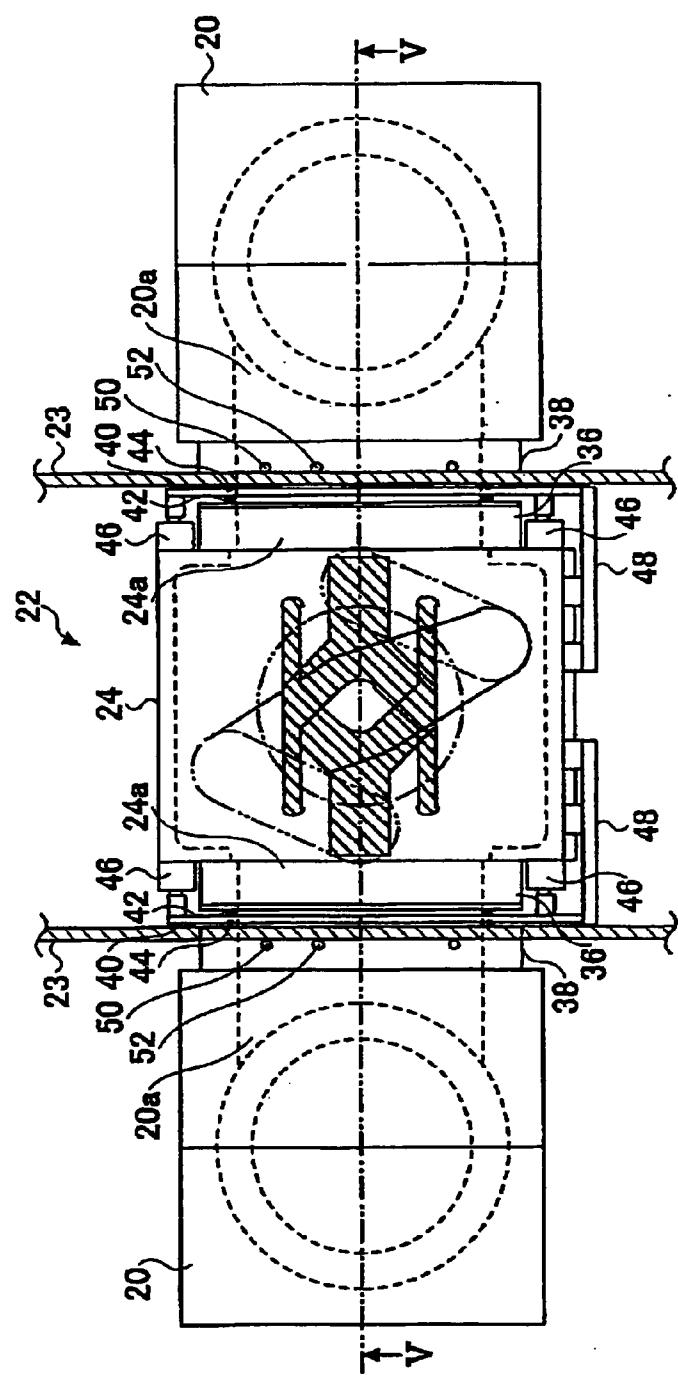


FIG.5

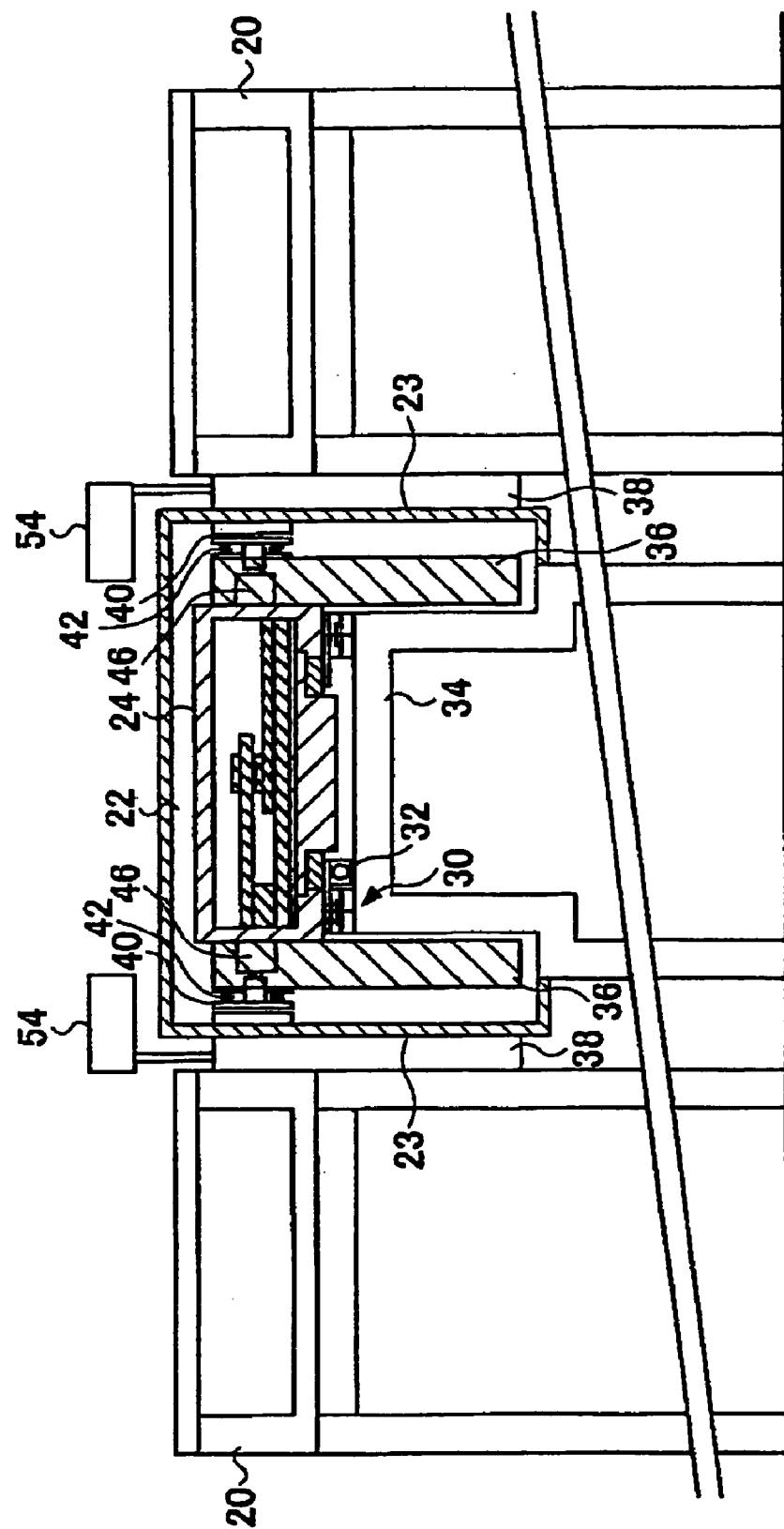


FIG. 6

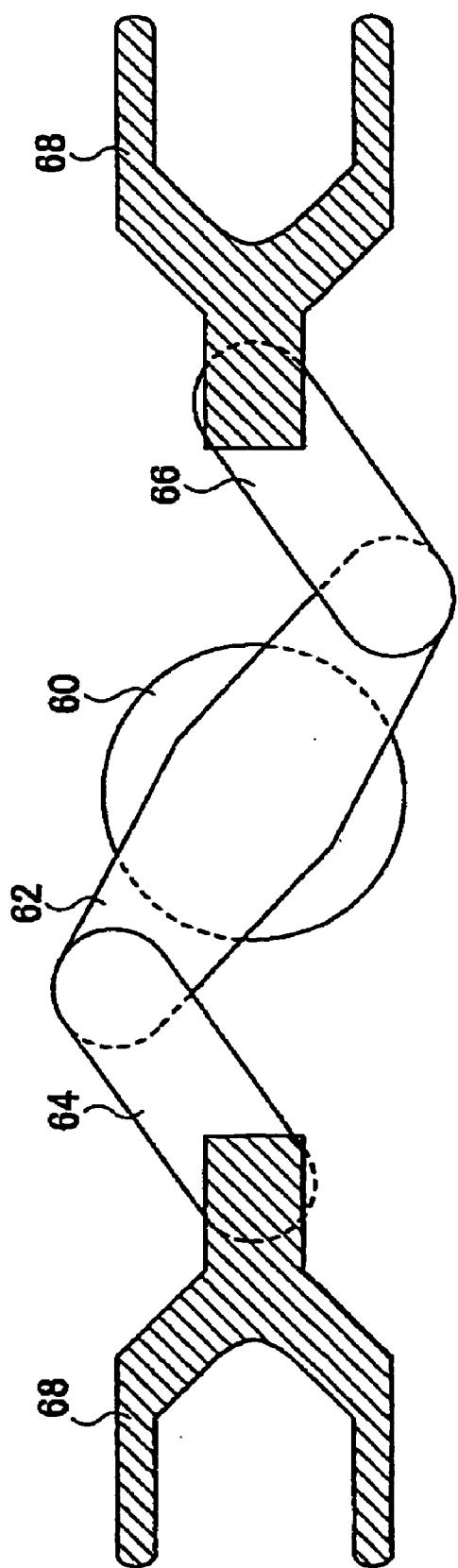


FIG.7

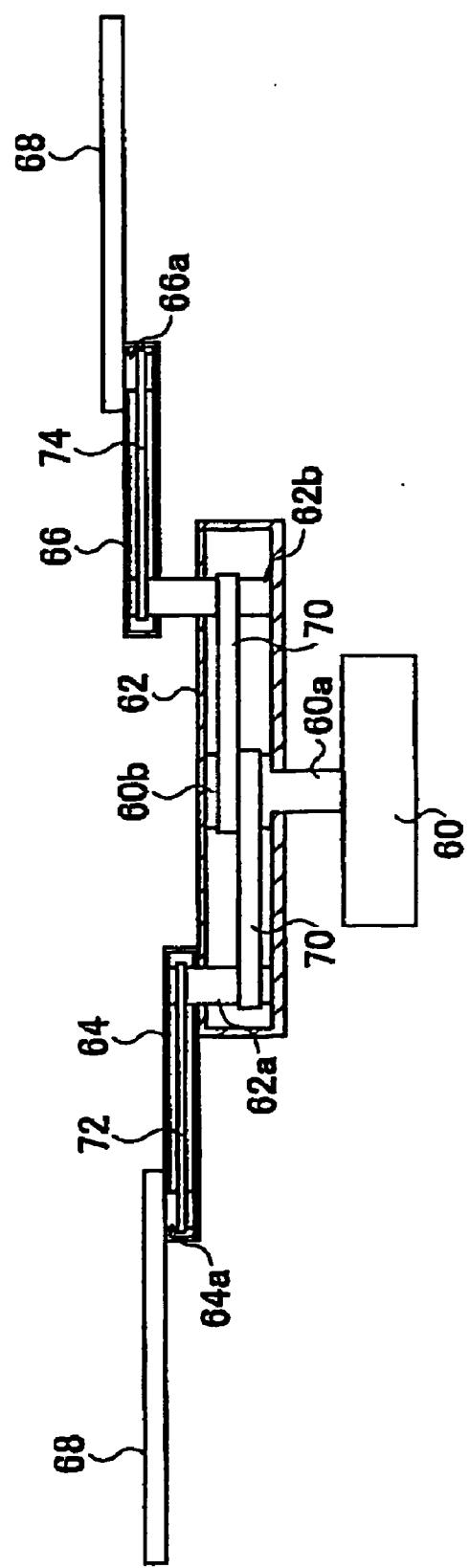


FIG.8

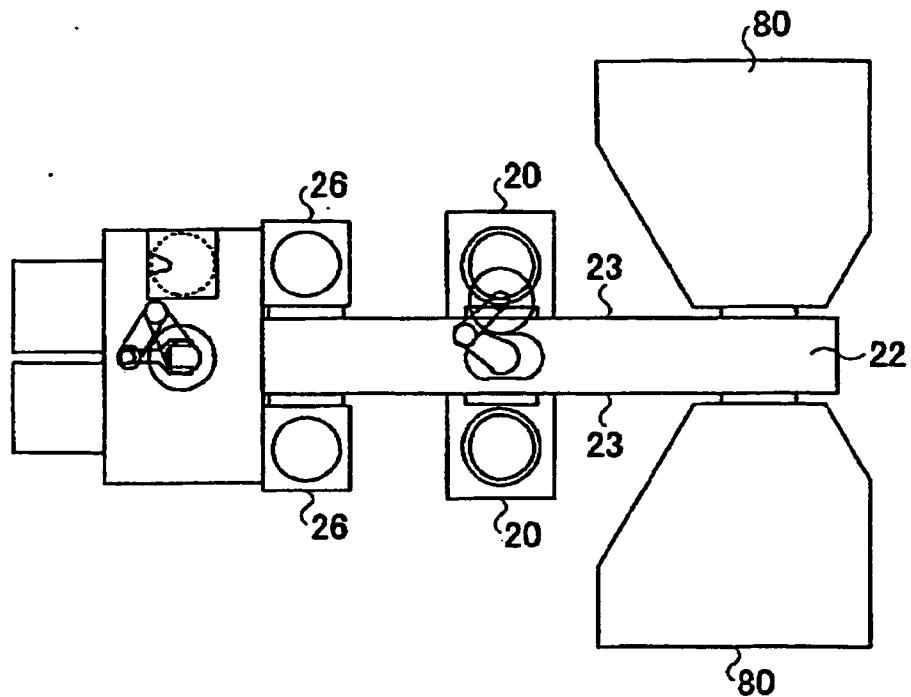


FIG.9

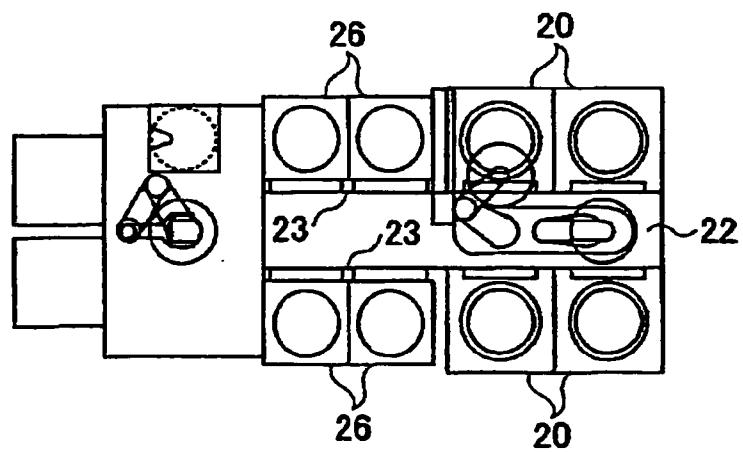


FIG.10

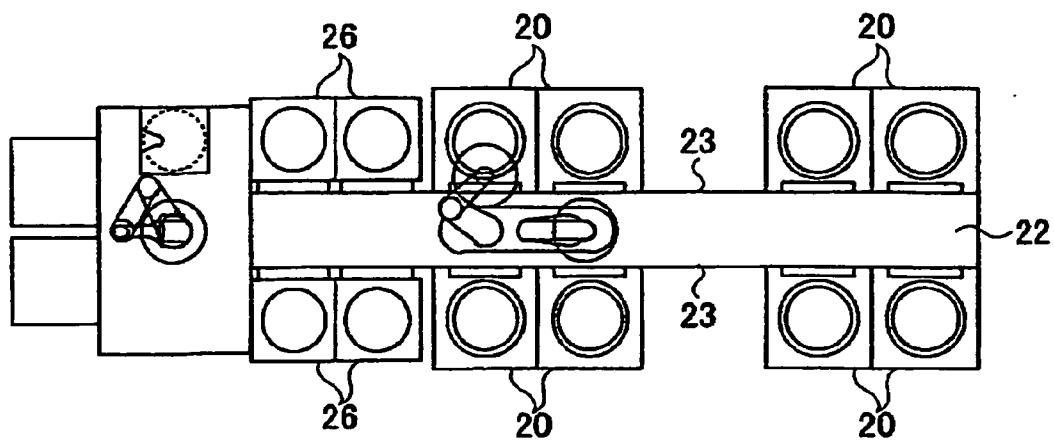
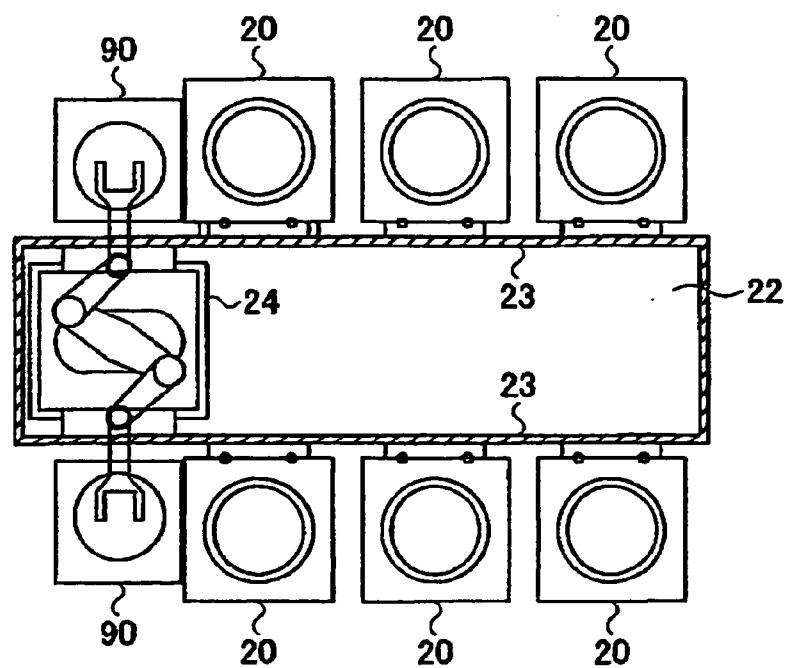


FIG.11



SUBSTRATE PROCESSING DEVICE

TECHNICAL FIELD

[0001] The present invention relates to substrate processing apparatuses and, more particularly, to a substrate processing apparatus having a moving mechanism that conveys a substrate such as a semiconductor wafer or the like to a process chamber that processes the wafer under a predetermined environment.

BACKGROUND ART

[0002] In processing a substrate such as a semiconductor wafer or the like, many processes to supply a process gas under a predetermined reduced pressure atmosphere are used. In many cases, such a process is performed while placing a substrate in a process chamber which can maintain a reduced pressure atmosphere. Processing a substrate generally includes a plurality of processes, and a plurality of process chambers for performing those processes are connected to a substrate conveyance chamber and the substrate is carried into a process chamber and carried out of the process chamber by a conveyance mechanism such as a robot so as to be conveyed to another process chamber.

[0003] In such a substrate processing apparatus, it is general that a plurality of process chambers and a load-lock chamber are arranged around a conveyance chamber, and a robot in the conveyance chamber conveys a substrate via an arm. The load-lock chamber is a pressure adjusting chamber provided for carrying a substrate in the conveyance chamber or carrying a substrate out of the conveyance chamber. That is, since the conveyance chamber is connected to the process chambers, inside the conveyance chamber must be maintained under a reduced pressure atmosphere close to an environment inside the process chambers. Thus, it is so constructed to isolate a space inside the conveyance chamber by providing the load-lock chamber.

[0004] Although various processes are applied to a substrate, there may be a case in which a process time in each process differs greatly. In order to raise a throughput of substrate processing, it is preferable that the process time required for each process is almost equal. Therefore, in order to process substrates of the same number of sheets for the same process time, it is general to provide a plurality of process chambers to perform concurrently for a process taking a long process time. That is, it is preferable to adjust a number of substrates being processed per unit time is the same for each process.

[0005] FIG. 1 is a plan view showing an example of a conventional substrate processing apparatus provided with a plurality of process chambers for performing the same process. The substrate processing apparatus shown in FIG. 1 comprises a load-lock chamber 2, a conveyance chamber 4 connected to one side of the load-lock chamber 2 and six process chambers 6 connected to remaining three sides of the load-lock chamber 2.

[0006] The load-lock chamber 2 is capable of accommodating two sheets of substrate at the same time. Two transfer robots 8 for carrying the substrates into the load-lock chamber 2 or carrying the substrates out of the load-lock chamber 2 are installed in the vicinity of the load-lock chamber 2.

[0007] The interior of the conveyance chamber 4 connected to the load-lock chamber 2 is capable of being maintained at a reduced pressure environment, and when the load-lock chamber 2 is set to the predetermined reduced pressure environment (degree of vacuum), the rotating-type transfer robot 10 in the conveyance chamber 4 picks up and holds substrates in the load-lock chamber 2, and conveys the substrates to the process chamber 6.

[0008] The transfer robot 10 has two arms and is capable of transferring two substrates simultaneously. Therefore, two sets of process chamber 6 are connected to the conveyance chamber 4 in a state where the two sets are arranged side by side so that two sheets of substrate held by the two arms are carried into the two process chambers, respectively, at the same time.

[0009] A total of six sets of process chamber 6 of which two each are connected to the three sides of the conveyance chamber 4 other than the side to which the load-lock chamber 2 is connected, respectively, so as to reduce a process time per one sheet of substrate in the process step by performing the process by the six sets of process chamber 6.

[0010] It is also suggested to provide a transfer mechanism having arms to hold substrates and capable of linearly moving within the conveyance chamber 4 instead of the above-mentioned rotating type transfer robot.

[0011] Moreover, there is also suggested a method of conveying substrates from a load-lock chamber to a process chamber by a conveyance case having a transfer mechanism (for example, refer to Patent Documents 1 and 2). In this method, there is no need to arrange a transfer robot in a conveyance chamber, and a number of process chambers is not limited by the transfer robot and the configuration of the conveyance chamber, thereby enabling a reduction in an installation area of an entire substrate processing apparatus.

[0012] The following patent documents disclose techniques relating to prior art of the present invention.

[0013] (Patent Document 1) Japanese Laid-Open Patent Application No. 3-184331

[0014] (Patent Document 2) Japanese Laid-Open Patent Application No. 6-97258

[0015] In the above-mentioned substrate processing apparatus shown in FIG. 1, since it is necessary to arrange the process chambers and the load-lock chamber to surround the conveyance chamber, there is a limit in the number of process chambers that can be arranged. In the example shown in FIG. 1, the number of process chambers connectable to the conveyance chamber 4 is six at the maximum.

[0016] Although the number of sides to which the process chambers are connectable is increased by making the configuration of the conveyance chamber to be a polygonal shape of more than hexagon, one side may be smaller than a size of the process chamber, and, as a result, the process chamber cannot be connected.

[0017] Thus, there is a limit in the number of process chambers that can be provided to the conventional substrate processing apparatus, and there is a problem in that it cannot deal with a process to continuously performing many steps or a process to concurrently perform a large amount of processes each having one or plurality of steps.

[0018] When a transfer mechanism of a movable type such as a linear-type conveyance mechanism instead of the rotating-type transfer robot, the restriction in the number of process chambers due to the configuration of the conveyance chamber is eliminated. However, since the transfer mechanism moves in the conveyance chamber which is to be maintained at a vacuum and clean atmosphere, the transfer mechanism may be a generation source of particles. Especially, there is a problem in that particles may be generated by a cable for supplying electric power to the transfer mechanism being drawn, which is a cause of pollution of substrates.

[0019] Moreover, if the number of process chambers is increased, a space of the conveyance chamber is also increased, and there is a problem in that a pump having a large exhaust capacity is needed to maintain such as large space under a reduced pressure environment, which increases a cost. Further, there also is a problem in the entire apparatus is enlarged by enlargement of the conveyance chamber, which results in an increase in an area occupied by the apparatus.

[0020] The present invention was made in view of the above-mentioned problems, and an object of the present invention is to provide a substrate processing apparatus which can convey substrates to a plurality of process chambers while maintaining an atmosphere of substrates to be processes at a predetermined environment and reduce an installation area of the entire apparatus.

MEANS TO SOLVE THE PROBLEMS

[0021] In order to solve the above-mentioned problems, there is provided according to the present invention a substrate processing apparatus comprising: a plurality of process chambers for applying a process to substrate accommodated therein; a conveyance case that accommodates the substrates in an isolated state from an external atmosphere and conveys the accommodated substrates to the process chambers; and a moving mechanism that moves the conveyance case along a moving path, wherein said plurality of process chambers are arranged in an aligned state on both sides of the moving path of said conveyance case, and said conveyance case has two substrate carry-in and carry-out ports in response to substrate carry-in and carry-out ports of said process chambers arranged and aligned in two rows.

[0022] In the above-mentioned substrate processing apparatus, it is preferable that said conveyance case includes a substrate transfer mechanism having first and second arms so that the first arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on one side and the second arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on opposite side. Additionally, it is preferable that said substrate transfer mechanism includes a single electric motor and a power transfer mechanism that transfer power of the electric motor to said first and second arms, and said first and second arms are configured and arranged to move symmetrically in directions opposite to each other by the power of the single electric motor.

[0023] Additionally, in the substrate processing apparatus according to the present invention, the process chambers may be configured and arranged to process the substrates under a reduced pressure, and said conveyance case may be

configured and arranged to be air-tight so that an interior thereof is maintained at a reduced pressure environment. Further, said conveyance case is preferably configured and arranged to be connectable to a vacuum exhaust mechanism at a position where the substrates are carried-in from outside. Additionally, a load-lock chamber may be arranged at a position along said moving path, the load-lock chamber so as to maintain an atmosphere of the substrates being conveyed by said conveyance case at a reduced pressure environment beforehand, and said conveyance case may be configured and arranged to convey the substrates between said load-lock chamber and said process chambers while maintaining the interior at the reduced pressure environment.

[0024] Further, said conveyance case and said moving mechanism may be located in a conveyance chamber configured and arranged to be air-tight so as to maintain an interior thereof at a reduced pressure environment, or said conveyance case and said moving mechanism may be located in a conveyance chamber in which an inert gas is filled. Additionally, it is preferable that said conveyance case and said moving mechanism are located in a conveyance chamber which has an interior being maintained at an atmospheric pressure or in which an inert gas is filled, and a vacuum exhaust port is provided to substrate carry-in and carry-out ports of said conveyance case so as to form a vacuum in a space formed between the substrate carry-in and carry-out ports of said conveyance case and substrate carry-in and carry-out ports of said process chambers in a state where the substrate carry-in and carry-out ports of said conveyance case are connected to the substrate carry-in and carry-out ports of said process chambers.

[0025] Additionally, there is provided according to the present invention a conveyance case that conveys substrates to a plurality of process chambers arranged in alignment on both sides in a longitudinal direction of a conveyance chamber, the conveyance case accommodating the substrates in an isolated state from an external atmosphere and having two substrate carry-in and carry out ports in response to substrate carry-in and carry-out ports of said process chambers arranged in alignment in two rows.

[0026] It is preferable that the two substrate carry-in and carry-out ports of said conveyance case are connected at the same time to the substrate carry-in and carry-out ports of the two process chambers of the process chambers aligned in two rows, and a substrate transfer mechanism is provided to carry-in and carry-out the substrates at the same time to the two process chambers on both sides.

[0027] Additionally, it is preferable that the conveyance case according to the present invention comprises a substrate transfer mechanism having first and second arms so that the first arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on one side and the second arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on opposite side. It is preferable that said substrate transfer mechanism includes a single electric motor and a power transfer mechanism that transfers power of the electric motor to said first and second arms, and said first and second arms are configured and arranged to move symmetrically in directions opposite to each other by the power of the single electric motor.

EFFECT OF THE INVENTION

[0028] As mentioned above, according to the present invention, the substrates can be carried to the plurality of process chambers while maintaining an atmosphere of the substrates to be processed at a predetermined environment, and an installation area of the entire apparatus can be reduced. Additionally, there is no restriction in the number of process chambers to connect due to a configuration of the conveyance chamber, and an arbitrary number of process chambers and different processing apparatuses may be arranged along a conveyance path.

BRIEF DESCRIPTION OF THE DRAWINGS

[0029] FIG. 1 is an outline plan view showing an entire structure of a conventional substrate processing apparatus.

[0030] FIG. 2 is an outline plan view showing an entire structure of a substrate processing apparatus according to a first embodiment of the present invention.

[0031] FIG. 3 is a plan view showing a state where a conveyance case is connected to a load-lock chamber in the substrate processing apparatus shown in FIG. 2.

[0032] FIG. 4 is a plan view showing a state where the conveyance case is connected to a process chamber in the substrate processing apparatus shown in FIG. 1.

[0033] FIG. 5 is a cross-sectional view taken along a line V-V in FIG. 4.

[0034] FIG. 6 is a plan view of a transfer mechanism provided in the conveyance case.

[0035] FIG. 7 is a cross-sectional view of the transfer mechanism shown in FIG. 6.

[0036] FIG. 8 is an outline plan view showing a first variation of the substrate processing apparatus shown in FIG. 2.

[0037] FIG. 9 is an outline plan view showing a second variation of the substrate processing apparatus shown in FIG. 2.

[0038] FIG. 10 is an outline plan view showing a third variation of the substrate processing apparatus shown in FIG. 2.

[0039] FIG. 11 is an outline plan view of a substrate processing apparatus according to a second embodiment of the present invention.

EXPLANATION OF REFERENCE NUMERALS

- [0040] 20 process chamber
- [0041] 20a conveyance port
- [0042] 22 conveyance chamber
- [0043] 23 sidewall
- [0044] 24 conveyance case
- [0045] 24a conveyance port
- [0046] 26 load-lock chamber
- [0047] 28 transfer robot
- [0048] 30 linear guide

- [0049] 32 lead screw
- [0050] 34 frame
- [0051] 36, 38 gate valve
- [0052] 40 connection plate
- [0053] 42 bellows
- [0054] 44 O-ring
- [0055] 46 air cylinder
- [0056] 48 linear guide
- [0057] 50 vacuum exhaust port
- [0058] 52 purge port
- [0059] 54 vacuum sensor
- [0060] 60 electric motor
- [0061] 60b, 62a, 62b, 64a, 66a synchronous pulley
- [0062] 62 common arm
- [0063] 60a rotational shaft
- [0064] 64 first arm
- [0065] 66 second arm
- [0066] 68 end-effector
- [0067] 70, 72, 74 timing belt
- [0068] 80 processing apparatus
- [0069] 90 cassette placement stage

BEST MODE FOR CARRYING OUT THE INVENTION

[0070] Next, a description will be given, with reference to FIG. 2, of a substrate processing apparatus according to a first embodiment of the present invention. FIG. 2 is a plan view of the substrate processing apparatus according to the first embodiment of the present invention.

[0071] The substrate processing apparatus shown in FIG. 2 is an apparatus for applying a process to substrates such as semiconductor wafers or the like under a reduced pressure in a plurality of process chambers 20. The plurality of process chambers 20 (six sets in FIG. 2) are connected to sidewalls constituting a conveyance chamber 22. The conveyance chamber 22 is constituted to be air-tight, and a conveyance case 24 and a moving mechanism, which moves the conveyance case 24, are provided inside the conveyance chamber 22. Accordingly, a moving path along which the conveyance case 24 moves is formed in the conveyance chamber 22, and the process chambers 20 are arranged in alignment on both sides of the moving path. The conveyance case 24 has a transfer mechanism as mentioned later so that exchange of substrates can be performed with the process chambers 20.

[0072] A load-lock chamber 26 is located at an end of each row of the process chambers 20 so that exchange of substrates can be performed with the conveyance case 24 as shown in FIG. 3. When conveying substrates to the processing chambers 20, the substrates are carried in a load-lock chamber 26 from outside, and gases in the load-lock chamber 26 are evacuated so as to set in a predetermined degree of vacuum. The carry-in of the substrates into the load-lock

chamber 26 is performed by a transfer robot 28 under an atmospheric pressure environment (an area indicated by double-dashed chain lines in FIG. 2) which is outside the substrate processing apparatus.

[0073] When the substrates are carried in the load-lock chamber 26 and the load-lock chamber 26 reaches the predetermined degree of vacuum, the conveyance case 24 moves to a position facing the load-lock chamber 26, and substrate carry-in and carry-out ports of the load-lock chamber 26 and carry-in and carry-out ports of the conveyance case 24 are connected air-tightly.

[0074] The process chambers 20 are aligned in two rows on both sides of the conveyance chamber 22 so that the conveyance case 24 is arranged to be located and moved between the rows. Accordingly, two substrate carry-in and carry-out ports are provided to the conveyance case 24 so as to be simultaneously connected to the load-lock chambers 26 on both sides. A transfer mechanism including two transfer arms is provided in the conveyance case 24 so as to hold the substrates in the load-lock chambers 26 on both sides by the transfer arms and carry the substrates into the conveyance case 24 (refer to FIG. 3). Thereafter, the conveyance opening of the conveyance case 24 is closed, and the conveyance case 24 is moved in a direction to the process chambers 20 by the transfer mechanism.

[0075] The conveyance case 24 stops at a position facing the target process chambers 20, and the substrate carry-in and carry-out ports of the conveyance case 24 and the substrate carry-in and carry-out ports of the process chambers 20 concerned are connected airtightly, and the substrates in the conveyance case 24 are carried in the process chambers 20 concerned by the transfer arms (refer to FIG. 2).

[0076] The conveyance case 24, which handed the substrates to the process chambers 20, moves to the position facing the load-lock chambers 26 again so as to receive substrates or receive substrates that have been processed from the process chambers 20, which has completed the process, and conveys the substrates to the load-lock chambers 26.

[0077] The conveyance case 24 repeats the above-mentioned operation. If the conveyance case 24 is stopped and is connected to the process chambers 20, the conveyance case 24 is maintained airtight as well as the process chambers 20 and is maintained airtight while moving. Accordingly, the substrates being conveyed are not exposed to an atmosphere, and the inside the conveyance case 24 can always be maintained at a reduced pressure environment.

[0078] Accordingly, when connecting the conveyance case 24 to the load-lock chambers 26 or the process chambers 20, there is no need to perform a vacuum exhaust at each time a connection is made since the inside of the conveyance case 24 is maintained at the reduced pressure environment.

[0079] In the present embodiment, the process chambers 20 are arranged in alignment on both sides of the moving path of the conveyance case 24 in the conveyance chamber 22, and the load-lock chambers 26 are arranged on both sides of the moving path one on each side. Thus, the conveyance case 24 is provided with the substrate carry-in and carry-out ports (hereinafter, referred to as conveyance

ports) on both left and right sides of the moving direction at one on each side so that two substrates are simultaneously conveyed and simultaneously supplied to the process chambers 20 on both sides, thereby performing the conveyance of substrates efficiently.

[0080] Additionally, since the transfer mechanism is accommodated in the conveyance case 24 during conveyance, the conveyance chamber 22 merely define a space for moving the conveyance case 24 and there is no need to acquire a movable area of the transfer mechanism in the conveyance chamber 22. Thus, an installation area of the conveyance chamber 22 can be made as small as possible, which can reduce the installation area of the entire substrate processing apparatus.

[0081] Here, a description will be given, with reference to FIG. 4 and FIG. 5, of the moving mechanism of the conveyance case 24 and the connection mechanism between the conveyance case 24 and the process chamber 20.

[0082] FIG. 4 is a plan view showing a state where the conveyance case 24 is connected to the process chamber 20 in the substrate processing apparatus shown in FIG. 1. FIG. 5 is a cross-sectional view taken along a line V-V in FIG. 4.

[0083] First, a description will be given of the moving mechanism of the conveyance case 24. The moving mechanism guides and drives the conveyance case 24 to move linearly within the conveyance chamber 22. The moving mechanism comprises, as shown in FIG. 5, a linear guide 30 that guides the conveyance case 24 to move linearly and a lead screw 32 that drives the conveyance case 24. The linear guide 30 and the lead screw 32 are provided between the conveyance case 24 and a lower frame 34.

[0084] The lead screw 32 is driven by an electric motor (not shown in the figure), and converts a rotational movement to a liner movement by a screw mechanism. The conveyance case 24 moves linearly while being guided by the linear guide 30 by the drive force in the direction of the linear movement. By changing the direction of rotation of the lead screw 32, the direction of movement of the conveyance case 24 can be changed to an opposite direction.

[0085] Next, a description will be given of the connection mechanism between the conveyance case 24 and the process chamber 20. In order to isolate an interior from an atmosphere and maintain airtight, the conveyance case 24 is provided with gate valves 36 for closing conveyance ports 24a. Since the conveyance case 24 has conveyance ports 24a, one on each of left and right sides, the gate valves 36 are provided one on each of left and right sides.

[0086] Additionally, gate valves 38 are provided to conveyance ports 20a of the process chambers 20. The conveyance case 24 is stopped at a position where the gate valves 36 of the conveyance case 24 face the gate valves 38 of the process chambers 20, and the interior of the conveyance case 24 and the interiors of the process chambers 20 are communicated with each other by opening the gate valves 36 and 38. It should be noted that since a gap exists between the gate valves 36 and 38, it is needed to connect airtightly the conveyance ports 24a of the conveyance case 24 and the conveyance ports 20a of the process chambers 20 before opening the gate valves 36 and 38.

[0087] Thus, in the present embodiment, a connection plate 40 and a bellows 42 are mounted to an outer side of the

connection port **24a** of the conveyance case, and the airtight connection is achieved by pressing the connection plate **40** against a peripheral portion of the conveyance port **20a** of the process chamber **20**. The bellows **42** is provided between the connection plate **40** and the side surface of the gate valve **36** so as to maintain a space between the connection plate **40** and the gate valve **36** airtight. Additionally, an O-ring **44** is attached to a surface of the connection plate **40** opposite to the process chamber **20** so as to achieve the airtight connection when the connection plate **40** is pressed against the gate valve **38**.

[0088] The connection plate **40** is attracted on the side of the conveyance case **24** while the conveyance case **24** is moving, and the connection plate **40** is pressed against the gate valve **38** after the conveyance case **24** is stopped at the position facing the process chamber **20** and the gate valves **36** and **38** are in an opposing state. The connection plate **40** is driven by an air cylinder **46** attached to the conveyance case **24**. That is, after the conveyance case **24** stops while facing the process chamber **20**, the connection plate **40** is moved relative to the gate valve **38** of the process chamber **20** by driving the air cylinder **46** and is pressed. Although the connection plate **40** is supported by the air cylinder **46**, it is preferable that the connection plate **40** is attached to the liner guide **48** so as to move parallel to the side surface of the gate valve **38**.

[0089] Even if the connection plate **40** is moved in a direction separating from the gate valve **38**, the airtightness between the connection plate **40** and the gate valve **36** is maintained by the bellows **42**. When the connection plate **40** reaches the gate valve **38**, the O-ring **44** is pressed between the connection plate **40** and the side surface of the gate valve **38**, and the airtight connection is achieved. Thus, the connection ports **24a** of the conveyance case **24** and the connection ports **20a** of the process chambers **20** are connected airtight. In this state, when the gate valves **36** and **38** are opened, the interior of the conveyance case **24** and the interiors of the process chambers **20** are communicated with each other, which permits exchange of substrates between the conveyance case **24** and the process chambers **20**. In this circumstance, since the conveyance case **24** and the process chambers **20** are connected airtight as mentioned above, there is no gas flowing into or no deterioration of the reduced pressure environment of the conveyance case **24** and the process chambers **20**.

[0090] It should be noted that in a case where the inside of the conveyance chamber **22** is at an atmospheric pressure or filled by an inert gas, the space between the gate valve **36** and gate valve **38** (including a thickness of the connection plate **40** and a stroke of the bellows **42**) cannot to be a reduced pressure environment. Hereinafter, this space is referred to as a connection space. Thus, it is needed to vacuum the connection space after making the airtight connection by pressing the connection plate **40** against the gate valve **38**.

[0091] Thus, in the present embodiment, a vacuum exhaust port **50** is provided to the gate valve **38** so as to vacuum the above-mentioned space. Additionally, it is preferable to constitute that a purge port **52** is provided together with the vacuum exhaust port **50** so as to set the above-mentioned space at a pressure equal to the atmosphere when canceling the airtight connection so that the connection plate **40** is easily separated from the gate valve **38**.

[0092] Moreover, since it is needed to open the gate valves **36** and **38** after the connection space is set to a predetermined degree of vacuum, it is preferable to provide a vacuum sensor **54** that detects a degree of vacuum of the connection space.

[0093] It should be noted that the load-lock chamber **26** provided in the row of the process chambers **20** also has a connection mechanism the same as the above-mentioned connection mechanism provided to the process chambers **20**, and the load-lock chamber **26** and the conveyance case **24** can be connected airtight. Accordingly, the substrates conveyed into the load-lock chamber **26** from outside can be maintained in a predetermined atmosphere after maintained in the predetermined atmosphere in the load-lock chamber **26** and until conveyed to the process chambers **20** by the conveyance case **24**.

[0094] Next, a description will be given, with reference to FIG. 6 and FIG. 7, of the substrate transfer mechanism provided in the conveyance case **24**. FIG. 6 is a plan view of the transfer mechanism provided in the conveyance case **24**, and FIG. 7 is a cross-sectional view of the transfer mechanism.

[0095] The transfer mechanism comprises an electric motor **60** and a common arm **62** rotationally driven by the electric motor **60**. The common arm **62** is fixed to a rotational shaft **60a** of the electric motor at its center portion, and is rotatable about the center portion. A first arm **64** is attached to an end of the common arm **62**, and a second arm **66** is attached to the other end. Further, an end-effector **68** is attached to an end of each of the first arm **64** and the second arm **66**.

[0096] Synchronous pulleys **62a** and **62b** are provided on opposite ends of the common arm **62**, and are engaged with a synchronous pulley **60b** provided to the rotational shaft **60a** of the electric motor **60** via a timing belt **70**. The first arm **64** is fixed to an axis of the synchronous pulley **62a** so as to rotate with the synchronous pulley **62a**. Additionally, a synchronous pulley **64a** is attached to an end of the first arm **64**, and the synchronous pulley **64a** and the synchronous pulley **62a** are engaged with each other via a timing belt **72**. The end-effector **68** is fixed to the axis of the synchronous pulley **64a**. Similarly, the second arm **66** is fixed to an axis of the synchronous pulley **62b** so as to rotate with the synchronous pulley **62b**. Additionally, a synchronous pulley **66a** is attached to an end of the second arm **66**, and the synchronous pulley **66a** and the synchronous pulley **62b** are engaged with each other via a timing belt **74**. The end-effector **68** is fixed to the axis of the synchronous pulley **66a**.

[0097] According to the transfer mechanism of the above-mentioned structure, both end-effectors **68** can be linearly moved in opposite directions. That is, when the rotational shaft **60a** of the electric motor **60** is rotated, the end-effectors **68** linearly moves in opposite directions so as to separate away from the electric motor **60**, and when the rotation of the rotational shaft **60a** is reversed, they move linearly to return toward the electric motor **60**. According to such movements of the two end-effectors **68**, exchange of substrates can be performed with respect to two process chambers **20** located on both sides of the conveyance case **24**.

[0098] It should be noted that since the electric motor **60** moves together with the conveyance case **24**, a cable for

supplying electric power to the electric motor **60** extends from the conveyance case **24**, and the cable is pulled around due to the movement of the conveyance case **24**. In this case, particles may be generated due to the pull of the cable. In order to avoid such a problem, a small battery may be mounted on the conveyance case **24** so as to drive the electric motor **60**, and charge of the battery may be performed according to induction generation of a non-contact type.

[0099] As mentioned-above, in the present embodiment, the process chambers **20** are arranged three each on both sides of the conveyance chamber **22**, but the number of process chambers **20** is not limited to that, and an arbitrary number of process chambers **20** can be connected by elongating the conveyance chamber **22**.

[0100] Moreover, if the process performed in the process chamber **20** is a process performed under a reduced pressure, it is preferable that the interior of the conveyance chamber **22** is also set to a reduced pressure environment, but it is not always needed to set the interior of the conveyance chamber **22** to a reduced pressure environment, and may be set to an atmospheric pressure. Additionally, in consideration of a case where leak occurs from the conveyance chamber **22** to the conveyance case **24** or the process chambers **22**, an inert gas may be filled within the conveyance chamber **22**.

[0101] Moreover, although the space where the conveyance case **24** moves is surrounded by the conveyance chamber **22** in the present embodiment, it is not always necessary to provide the conveyance chamber **22**. The conveyance chamber **22** is suitable for setting the space where the conveyance case **24** moves to a reduced pressure environment or setting the space to be filled with an inert gas. Alternatively, it is preferable to provide the conveyance chamber **22** so as to prevent scattering of particles generated due to the movement of the conveyance case **24**. However, the conveyance chamber **22** is not an essential structural element in the present invention, and what is required is to provide a moving path for moving the conveyance case **24** between the process chambers **20** on both sides.

[0102] Additionally, although the transfer mechanism having the two arms operating at the same time is provided in the conveyance case **24** in the present embodiment, the transfer mechanism may have a single arm so as to transfer substrates to the left and right process chambers **20** in turn.

[0103] Next, a description will be given of a variation of the substrate processing apparatus according to the first embodiment of the present invention.

[0104] FIG. 8 is an outline plan view of a first variation of the substrate processing apparatus shown in FIG. 2. In this variation, process chambers **80** which perform a different process from that of the process chambers **20** are connected to the conveyance chamber **22**. Substrates processed in the process chambers **20** are further conveyed to the process chambers **80** by the conveyance case **24**, and are conveyed to outside from the substrate processing apparatus after performing a subsequent process. Accordingly, a plurality of processes can be applied to substrates in a single substrate processing apparatus.

[0105] FIG. 9 is an outline plan view showing a second variation of the substrate processing apparatus shown in FIG. 2. In this variation, the load-lock chamber **26** is divided

into two with respect to one row of the process chambers **20**. Additionally, two conveyance cases **24** are provided by being connected with each other. By constituting as mentioned above, if the transfer mechanism of the conveyance case **24** has two arms operable at the same time, four substrates can be conveyed simultaneously, which increases a throughput of substrate processing.

[0106] FIG. 10 is an outline plan view showing a third variation of the substrate processing apparatus shown in FIG. 2. In this variation, the conveyance chamber **22** is elongated in the structure shown in FIG. 9, and further process chambers **20** are added and connected to the conveyance chamber **22**. Thus, by elongating the conveyance chamber **22** constituting the moving path of the conveyance case **24**, more process chambers **20** can be connected to the conveyance chamber **22**, which raises a throughput of the substrate processing.

[0107] Next, a description will be given, with reference to FIG. 11, of a substrate processing apparatus according to the second embodiment of the present invention. FIG. 11 is an outline plan view of the substrate process apparatus according to the second embodiment of the present invention. In FIG. 11, parts that are the same as the part shown in FIG. 2 are given the same reference numerals, and descriptions thereof will be omitted.

[0108] The substrate processing apparatus shown in FIG. 11 comprises the conveyance chamber **22** and the process chambers **20** connected to the conveyance chamber **22**, and the conveyance case **24** moves in the conveyance chamber **22** so as to convey the substrates. This structure is the same as the structure of the substrate processing apparatus shown in FIG. 2.

[0109] In the present embodiment, cassette placement stages **90** are provided instead of the load-lock chambers **26**. Cassette that accommodates a plurality of substrates arranged in a vertical direction is placed on each of the cassette placement stages **90**. Each cassette placement stage **90** has a vertical moving mechanism for moving the cassette up and down. The cassette placement stages **90** are set under an atmospheric pressure atmosphere, and do not have a container which can achieve a reduced pressure environment such as the load-lock chamber **26**.

[0110] The conveyance case **24** is airtightly constituted like the above-mentioned first embodiment so as to isolate the inside from an outside atmosphere and to maintain a reduced pressure environment. Therefore, in case it moves in the inside of the conveyance chamber **22**, the inside of the conveyance case **24** can be maintained in a reduced pressure environment and is airtightly connected to the process chambers **20**.

[0111] However, since delivery of the substrate with the exterior is performed between the cassettes placed on the cassette placement stages **90**, it is performed under an atmospheric pressure. Therefore, after receiving the substrate from the cassette and closing the gate valve **36**, it is necessary to carry out evacuation of gas inside the conveyance case **24** so as to set a reduced pressure environment. That is, in the present embodiment, the conveyance case **24** has a structure to serve also as the load-lock chamber. Additionally, there is no need to provide a transfer robot outside the apparatus to carry substrates in and out of the load-lock chamber.

[0112] It should be noted that in the present embodiment, like the above-mentioned first embodiment, it is not always necessary to set inside the conveyance chamber 22 in a reduced pressure atmosphere. Additionally, what is required is to achieve a structure to move the conveyance case 24 between the process chambers 20 arranged in two rows, and it is not always necessary to provide the conveyance chamber 22 itself.

[0113] As mentioned above, in the substrate processing apparatus according to the second embodiment of the present embodiment, since the load-lock chamber can be omitted, the entire substrate processing apparatus becomes small and an installation area can be reduced.

1. A substrate processing apparatus comprising:
 - a plurality of process chambers for applying a process to substrate accommodated therein;
 - a conveyance case that accommodates the substrates in an isolated state from an external atmosphere and conveys the accommodated substrates to the process chambers; and
 - a moving mechanism that moves the conveyance case along a moving path,
 wherein said plurality of process chambers are arranged in an aligned state on both sides of the moving path of said conveyance case, and said conveyance case has two substrate carry-in and carry-out ports in response to substrate carry-in and carry-out ports of said process chambers arranged and aligned in two rows.

2. The substrate processing apparatus as claimed in claim 1, wherein said conveyance case includes a substrate transfer mechanism having first and second arms so that the first arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on one side and the second arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on opposite side.

3. The substrate processing apparatus as claimed in claim 2, wherein said substrate transfer mechanism includes a single electric motor and a power transfer mechanism that transfer power of the electric motor to said first and second arms, and said first and second arms are configured and arranged to move symmetrically in directions opposite to each other by the power of the single electric motor.

4. The substrate processing apparatus as claimed in claim 1, wherein said process chambers are configured and arranged to process the substrates under a reduced pressure, and said conveyance case is configured and arranged to be air-tight so that an interior thereof is maintained at a reduced pressure environment.

5. The substrate processing apparatus as claimed in claim 4, wherein said conveyance case is configured and arranged to be connectable to a vacuum exhaust mechanism at a position where the substrates are carried-in from outside.

6. The substrate processing apparatus as claimed in claim 4, wherein a load-lock chamber is arranged at a position along said moving path, the load-lock chamber so as to maintain an atmosphere of the substrates being conveyed by

said conveyance case at a reduced pressure environment beforehand, and said conveyance case is configured and arranged to convey the substrates between said load-lock chamber and said process chambers while maintaining the interior at the reduced pressure environment.

7. The substrate processing apparatus as claimed in claim 6, wherein said conveyance case and said moving mechanism are located in a conveyance chamber configured and arranged to be air-tight so as to maintain an interior thereof at a reduced pressure environment.

8. The substrate processing apparatus as claimed in claim 6, wherein said conveyance case and said moving mechanism are located in a conveyance chamber in which an inert gas is filled.

9. The substrate processing apparatus as claimed in claim 6, wherein said conveyance case and said moving mechanism are located in a conveyance chamber which has an interior being maintained at an atmospheric pressure or in which an inert gas is filled, and a vacuum exhaust port is provided to substrate carry-in and carry-out ports of said conveyance case so as to form a vacuum in a space formed between the substrate carry-in and carry-out ports of said conveyance case and substrate carry-in and carry-out ports of said process chambers in a state where the substrate carry-in and carry-out ports of said conveyance case are connected to the substrate carry-in and carry-out ports of said process chambers.

10. A conveyance case that conveys substrates to a plurality of process chambers arranged in alignment on both sides in a longitudinal direction of a conveyance chamber, the conveyance case accommodating the substrates in an isolated state from an external atmosphere and having two substrate carry-in and carry out ports in response to substrate carry-in and carry-out ports of said process chambers arranged in alignment in two rows.

11. The conveyance case as claimed in claim 10, wherein the two substrate carry-in and carry-out ports of said conveyance case are connected at the same time to the substrate carry-in and carry-out ports of the two process chambers of the process chambers aligned in two rows, and a substrate transfer mechanism is provided to carry-in and carry-out the substrates at the same time to the two process chambers on both sides.

12. The conveyance case as claimed in claim 10, comprising a substrate transfer mechanism having first and second arms so that the first arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on one side and the second arm performs carry-in and carry-out of the substrates with respect to the process chambers in the row on opposite side.

13. The conveyance case as claimed in claim 10, wherein said substrate transfer mechanism includes a single electric motor and a power transfer mechanism that transfers power of the electric motor to said first and second arms, and said first and second arms are configured and arranged to move symmetrically in directions opposite to each other by the power of the single electric motor.